

LNJ8L4C18RAA

Surface Mounting Chip LED

3528 (PLCC4) Type

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	190	mW
Forward current	I_F	70	mA
Pulse forward current *	I_{FP}	100	mA
Reverse voltage	V_R	5	V
Junction temperature	T_j	125	$^\circ\text{C}$
Thermal resistance	R_{th}	130	$^\circ\text{C}/\text{W}$
Operating ambient temperature	T_{opr}	-40 to +105	$^\circ\text{C}$
Storage temperature	T_{stg}	-40 to +125	$^\circ\text{C}$

■ Lighting Color

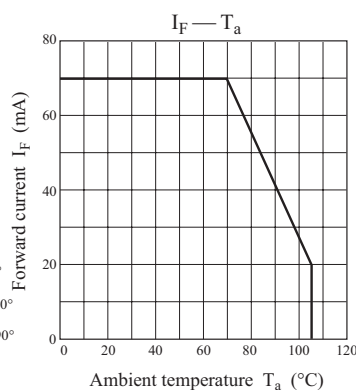
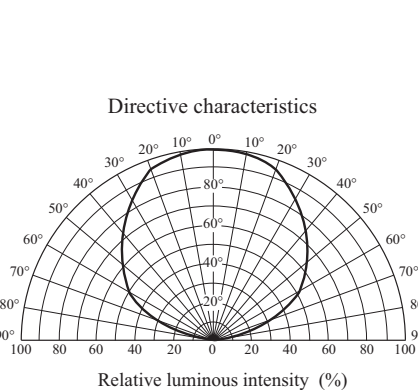
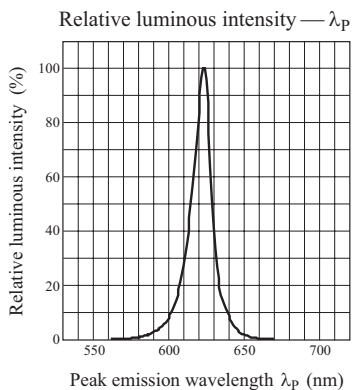
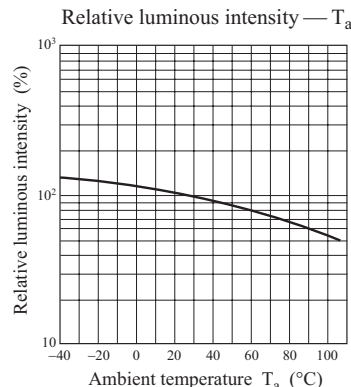
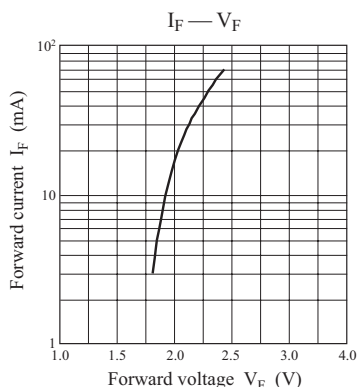
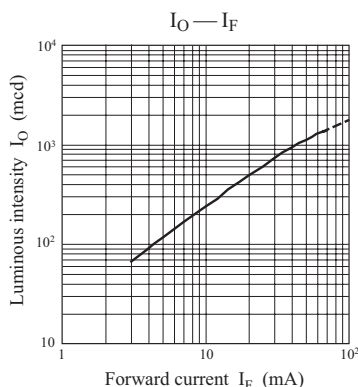
- Red

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

■ Electro-Optical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

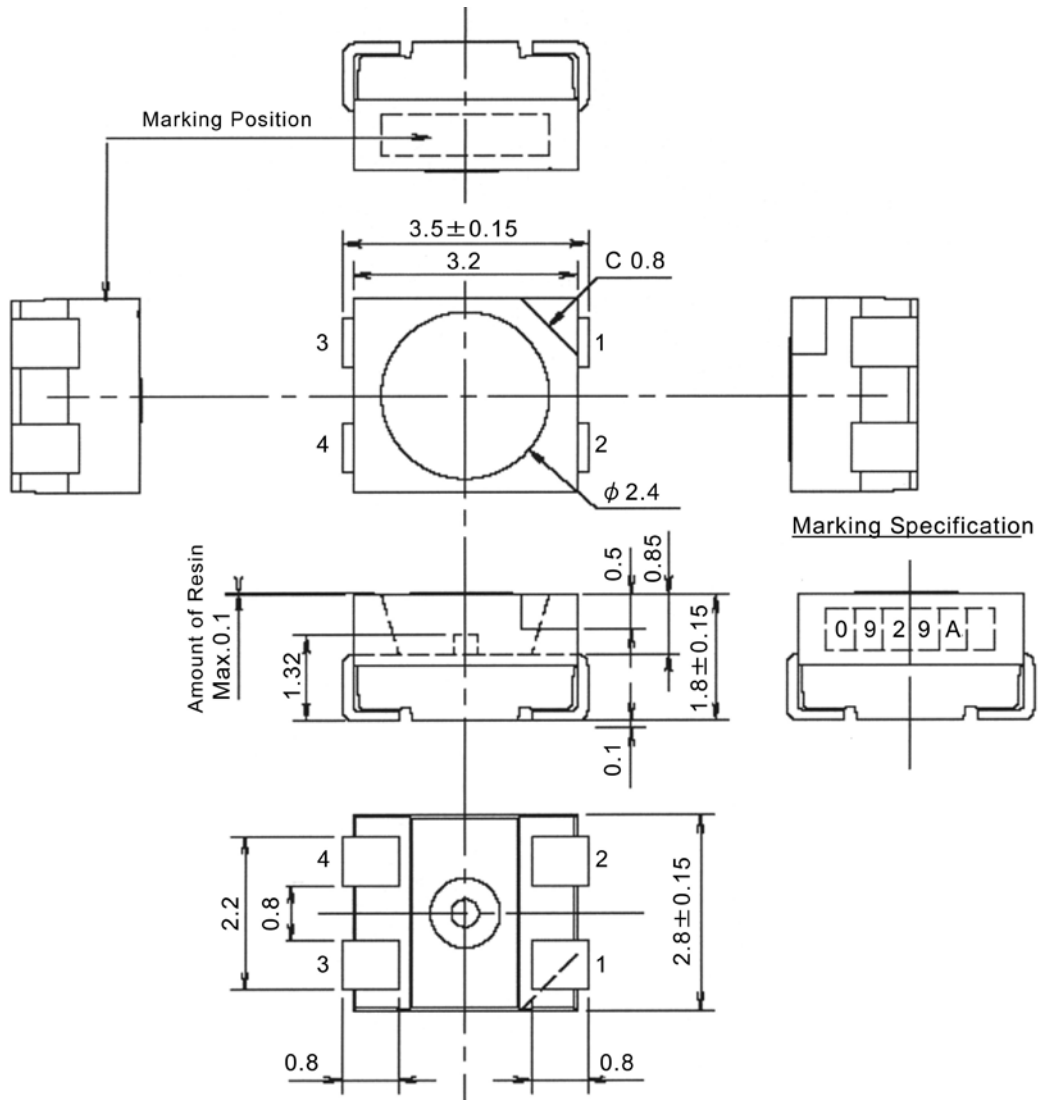
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity *1	I_O	$I_F = 50 \text{ mA}$	900	1130	1450	mcd
Reverse current	I_R	$V_R = 5 \text{ V}$			10	μA
Forward voltage *2	V_F	$I_F = 50 \text{ mA}$	2.05	2.30	2.65	V
Luminous flux *1	F	$I_F = 50 \text{ mA}$	(3.36)	(4.20)	(5.40)	lm
Peak emission wavelength	λ_p	$I_F = 50 \text{ mA}$		623		nm
Dominant emission wavelength *3	λ_d	$I_F = 50 \text{ mA}$	612	617	624	nm
Spectral half band width	$\Delta\lambda$	$I_F = 50 \text{ mA}$		20		nm

Note) *1: Measurement tolerance: $\pm 11\%$
 *2: Measurement tolerance: $\pm 0.15 \text{ V}$
 *3: Measurement tolerance: $\pm 2 \text{ nm}$



■ Package (Unit: mm)

LLDFTR4JL400



- Pin name
- 1: Cathode
- 2: Anode
- 3: N.C.
- 4: Anode

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